

ABSTRACT OF THE DISCLOSURE

To prevent short-circuit due to contact of bonding wires each other and to make a semiconductor device 5 compact. A semiconductor chip with a rectangular main surface may comprise: a first side composing the main surface; a second side opposed to the first side; a main electrode pad group composed of a plurality of main electrode pads, which plurality of main electrode pads is 10 arranged on the main surface along the first side; a first electrode pad group composed of a plurality of first electrode pads, which plurality of first electrode pads is arranged between the first side and the main electrode pad group; a second electrode pad group composed of a plurality 15 of second electrode pads, which plurality of second electrode pads is arranged on the main surface along the second side; a first interconnection connecting the main electrode pad with the first electrode pad; and a second interconnection connecting the main electrode pad with the 20 second electrode pad.